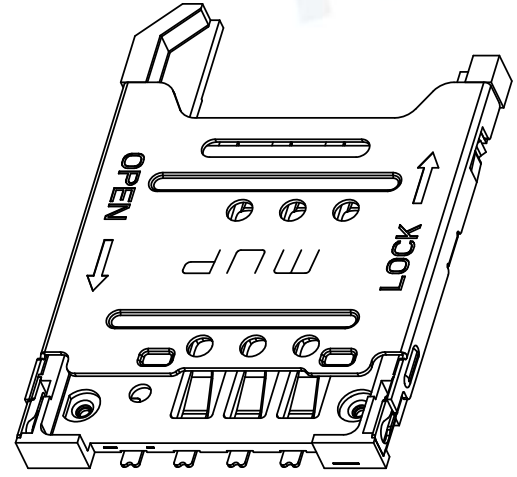
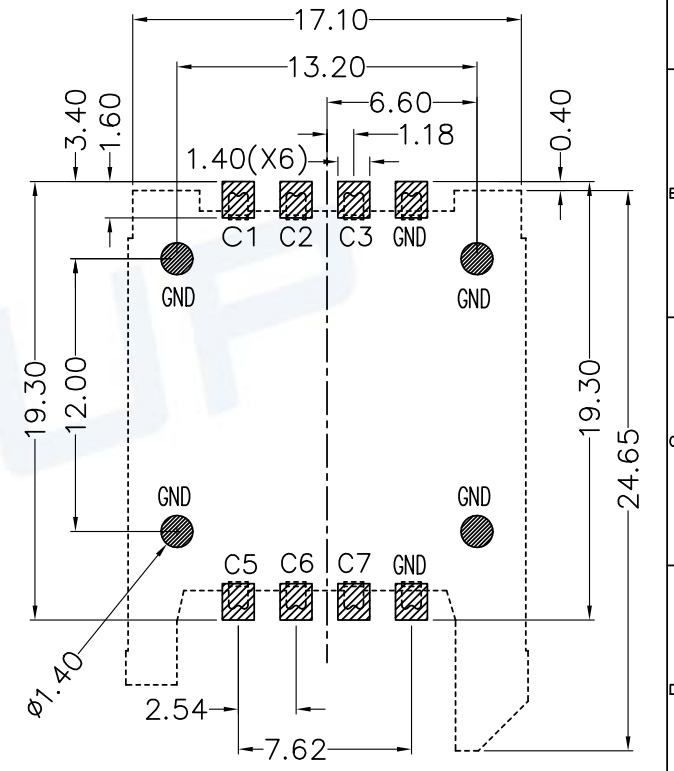
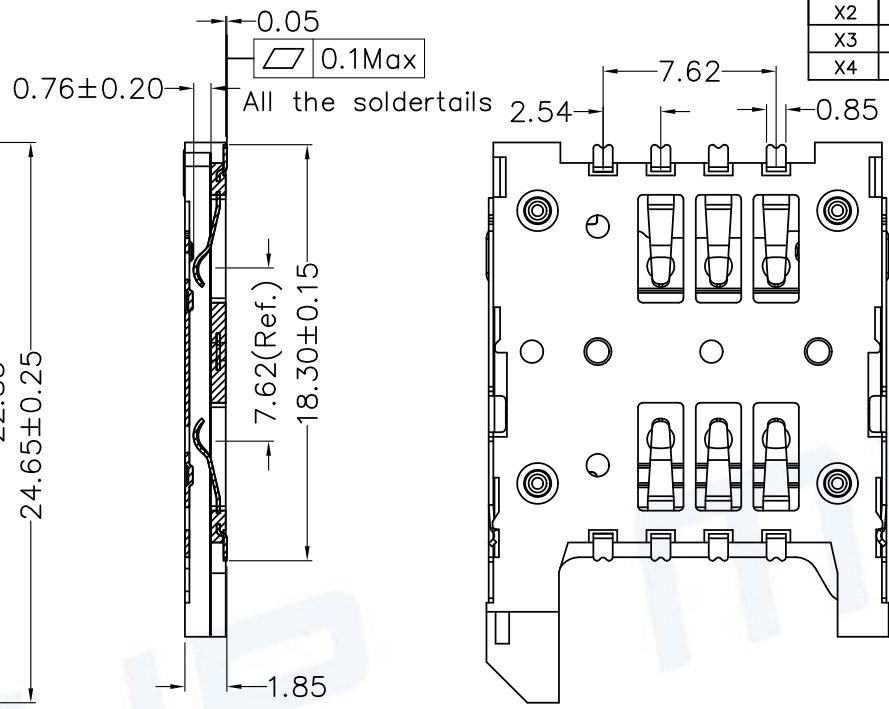
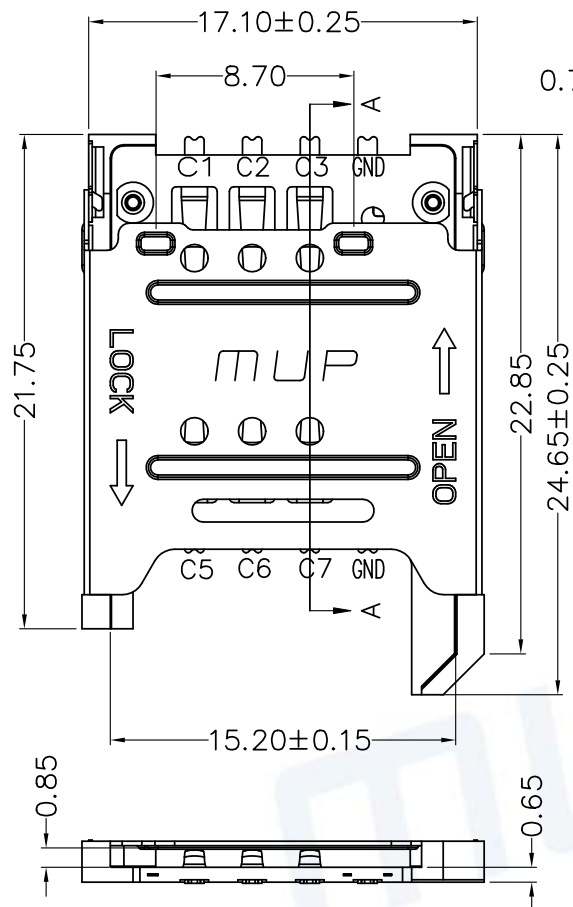


X1	design modify	key	2016.07.28
X2			
X3			
X4			



TECHNICAL CHARACTERISTICS

- General Characteristics
 Dimensions: 24.65LX17.10WX1.85H mm
 Weight: Approx0.90±0.2g
 Durability: 5,000 cycles min.
- Electrical Characteristics
 Contact resistance: 50mΩ typical, 100mΩ max
 Insulation resistance: >1000MΩ/500V DC
- Solderability
 Vapor phase: 215°C, 30sec.Max
 IR reflow: 250°C, 5sec.Max
 Manual soldering: 370°C, 3sec.Max
- Environmental Characteristics
 Operating temperature: -40°C~+85°C
 Operating humidity: 10%~+95%RH

RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE(TOLERANCE ±0.05)

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	BASE	1	Hi-temp Thermoplastic	Black UL94V-0
2	SHELL	1	Stainless steel	
3	DATA CONTACT	6	Copper Alloy	Contact area:Gold plated

MUP MUP INDUSTRIAL CO.,LTD.

Unless otherwise specified, other tolerance are:		NAME: SIM Card Connector	
X ±0.35	X* ±5*	MODEL NO: MUP C717-3	
X.X ±0.25	X.X* ±4*	TYPE: Without post 6p	
X.XX ±0.15	X.XX* ±3*	DRAWN: Zoey May.19.2017	
X.XXX ±0.10	X.XXX* ±2*	CHECKED: Jimmy May.19.2017	
PROJ.	UNIT: mm	SCALE: 1:1	DWG NO.: DWG-MUP-C717-003
CUSTOMER DRAWING			SHEET: 1/1
APPROVAL: Zoey May.19.2017			REVISION: X1

